



**Monday June 5 , 2000**  
**Company Press Release**

***High Connection Density's Rambus RIMMs demonstrated with Intel's 820 Chipset at Computex Taipei 2000***

SUNNYVALE, Calif.--(BUSINESS WIRE)--June 5, 2000-- High Connection Density (HCD), designer and manufacturer of custom, high-performance PC boards and inventor of high-frequency, high-density connector technology, will unveil for the first time its broad line of Rambus RIMM products June 5-9 at Computex Taipei 2000. During the Computex show, HCD will present its latest 32D Rambus RIMM module, and demonstrates RIMM with an Intel 820 Chipset system.

Having recently joined the growing list of Rambus partners, HCD is ready to launch a complete line of Rambus 128/144Mb RDRAM products from 4D to 32D RIMMs. In addition, leveraging 30 years of high-speed board design and a proprietary high-speed, high-density interconnect technology called SuperButton(tm), HCD offers a revolutionary small form factor RIMM that has twice the propagation delay performance with 30% cost reduction and 50% space saving in comparison with current designs.

HCD established its Taiwan manufacturing in October 1999. HCD's headquarter was recently opened in Silicon Valley. "Through careful planning and precise execution of building HCD's world-class manufacturing infrastructure, HCD now has two production lines in operation with production capacity for 250,000 memory modules per month. Our focus is on high-quality, thus full testing is performed on all manufactured products using high-speed, high-accuracy automated test systems. Monthly production volume is targeted for 500,000 RIMM modules by year end. We are completely ready for the Rambus RIMM market," said Dr. DC Hu, Ph.D., Executive Vice President of Manufacturing in HCD's Taiwan facility.

"HCD is ready to assist motherboard and computer manufacturers with current requirements for 128/144Mb Rambus RIMM and small form factor RIMM modules. HCD's strength is in its high-frequency design and high-quality manufacturing capability. In fact, HCD has already completed the design for 256/288Mb RIMMs and is ready to manufacture in high volume," said Jean-Luc Pelissier, Ph.D., President of HCD. "As the pressure increases to rapidly produce higher-performance, customized system modules, HCD's superb design validation service utilizing modeling, prototyping and sophisticated thermal, mechanical and high-speed electrical simulations combined with HCD's world-class high-volume manufacturing facilities enable HCD to provide turn-key "design-to-production" system modules to manufactures of high-end computers, telecom and consumer electronic appliances."



HIGH CONNECTION DENSITY, INC.

[www.hcdcorp.com](http://www.hcdcorp.com)

To see a presentation of HCD's 32D RIMM module, and a demonstration of HCD's standard design RIMM module with Intel's 820 Chipset at Computex Taipei 2000, please visit HCD at CMC booth in the Taipei World Trade Center venue Area A.

About High Connection Density, Inc.

High Connection Density, Inc. offers high-speed PCB design, verification and world-class manufacturing services providing quick, turn-key solutions to the high-end computer, consumer electronics and communication industry worldwide. HCD products include a family of standard and custom Rambus memory modules as well as DDR-SDRAM products. HCD's highly reliable Land Grid Array (LGA) superimposer technology, SuperButton, provides a minimum inductance, low-contact force, high pincount connector solution at low cost. For more information on HCD's innovative high-density SuperButton connector technology and, high-performance RIMM and SORIMM modules, please contact Angela Martin, at High Connection Density, Inc. 408/743-9700 Ext. 306